

## **Education**

- **THE UNIVERSITY OF CALIFORNIA, BERKELEY (UCB)**  
Ph.D.: Electrical Engineering and Computer Science July 2006  
Thesis: *Advanced Gate Processes for Nanoscale CMOS*  
Advisor: Prof. Tsu-Jae King Liu  
Major: *Electronic Device Physics and Processing*  
Minor: *Integrated Circuits* (Internal), *Quantum Mechanics* (External)
  
- **THE CHINESE UNIVERSITY OF HONG KONG (CUHK)**  
M. Phil.: Computer Science and Engineering July 2001  
Thesis: *Matching Properties and Applications of Compatible Lateral Bipolar Transistors*  
Advisor: Prof. Philip Heng Wai Leong  
  
B.Eng. (First class honor): Computer Engineering July 1999  
Minor: Business Administration  
Thesis: *Solving Constraint Satisfactory Problems using FPGAs*  
Advisor: Prof. Philip Heng Wai Leong

## **Professional Experience**

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|--|----------------------------------|------------------|
| <b>AMDT Endowed Chair Professor</b>                | <b>San Jose State University</b> | <b>2022-</b>     |
| <b>Associate Professor, Electrical Engineering</b> | <b>San Jose State University</b> | <b>2022-</b>     |
| <b>Assistant Professor, Electrical Engineering</b> | <b>San Jose State University</b> | <b>2018-2022</b> |
- Machine learning to discover physical models and debug process/circuit
  - Memory material characterization and simulation for leakage
  - Compact model for neuromorphic simulation
  - Calibration and simulation of novel WBG power device for electric vehicles and others
  - Electrically variable gate length transistor for sub-5nm nodes
  - Cryogenic calibration of CMOS devices for quantum computing interface
  - Reliability modeling of IoT Devices
- |  |                      |                    |
|--|----------------------|--------------------|
| <b>Visiting Scholar, TCAD Simulation, Prof. King-Liu's group</b> | <b>UC Berkeley</b>   | <b>2019-2020</b>   |
| <b>Senior Staff Applications Engineer</b>                        | <b>Synopsys Inc.</b> | <b>2009 – 2018</b> |
- **Reliability simulations on GaN defects and FinFET/nanowire NBTI**
  - **Novel power device and reliability simulations/modeling (GaN, Ga2O3, Diamond)**
  - **Expert/Champion on the following simulation tools**
    - SDevice, SProcess, SBand/Sub-band BTE, Monte Carlo Transport, NEGF, STT-RAM, ReRAM, Ab-initio to TCAD link
  - **A strong relationship with customers and understanding of the state of the art technologies**
  - **Technical know-how**
    - Delivered more than 20 technically successful TCAD simulation benchmarks on our customers' products including Si LDMOS, GaN devices, SiC IGBT, Avalanche Photo Diodes (APD), optoelectronics, ReRAM, HCI effects in SOI
  - **Pioneer Machine Learning in TCAD simulations and applications**
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|---------------------------------|-----------------------------------|--------------------|
| <b>MTS Integration Engineer</b> | <b>Spanion (AMD/Fujitsu) Inc.</b> | <b>2006 – 2009</b> |
|---------------------------------|-----------------------------------|--------------------|
- 45nm/32nm NOR flash memory technology process integration and development
  - Designed and verified 45nm test chip test structures layout

- STI, bitline, poly gate and CoSi modules optimization and Si defect studies
- Periphery device development and integration including simulation and bench measurements

**Internship** **Cypress Semiconductor** **2004 – 2005**

- Designed and applied non-melt and melt excimer laser annealing experiments to 200mm integration lots to mitigate poly gate depletion
- Owned 200mm integration with various novel gate and source/drain engineering splits

**6” CMOS baseline Process Development Team Member** **UCB Microfabrication Lab** **2002-2005**

- Performed full CMOS process flow and device simulations
- Performed bench characterizations: IV, CV, Oxide BV, mobility extraction, ring oscillator measurement

## Services

### University:

SJSU Academic Senator (10-EN-23) 2022-  
 Chair, SJSU Senate Policy Committee, Curriculum and Research, Spring 2023 -  
 SJSU Senate Policy Committee, Curriculum and Research, 2022-  
 Naming Committee, Spring 2023

### College of Engineering:

College Research Committee, College of Engineering, 2022-  
 Member, Strategic Plan Task Force, College of Engineering, 2022  
 College Assessment Committee, College of Engineering, 2018-2022  
 ESSC's Sophomore Success Program 2021  
 Associate Dean Search Committee, College of Engineering, 2021  
 Contributor, Strategic Plan, College of Engineering, 2019

### Department of EE:

Graduate Coordinator, MS Quantum Technology Program, 2023 –  
 Faculty Search Committee, 2022-2023 (opening closed)  
 Chair Review Committee, Electrical Engineering, 2021  
 Department Assessment Committee, Electrical Engineering, 2019-2022  
 Department Graduate Curriculum Committee, Electrical Engineering, 2019-  
 Department Undergraduate Curriculum Committee, Electrical Engineering, 2019-

## Professional Activities

### **Editor:**

- Associate Editor, IEEE Access (2020 - 2022)
- Guest Editor, Micromachines, special issue on "Novel Ultra Wide Bandgap Power Devices and Materials", 2020
- Guest Editor, Journal of Vacuum Science and Technology B, special issue on "Reliability and Stress-related Phenomena in Nano and Microelectronics", 2020

### **Conference Organizer:**

- Technical Program Committee (TPC), International Conference on Simulation of Semiconductor Processes and Devices (SISPAD) (2020-2021)
- Technical Program Committee (TPC), 2022 International Conference on Computer-Aided Design (ICCAD) (2022)

- Vice-Chair, 16th International Conference on Reliability and Stress-related Phenomena in Nano and Microelectronics (IRSP19)
- Member of International Program Committees for The IASTED International Conference on Control and Optimization of Renewable Energy Systems CORES 2019
- Workshop Moderator, “Circuit Reliability: Advanced nodes concerns and CAD tools flows” 2018 IEEE International Reliability Physics Symposium (IRPS)

### Senior Member of Institute of Electrical and Electronics Engineers (IEEE)

#### IEEE EDS-SCV/SF Chapter Officer

- Chair (2022-)
- Treasurer (2019-2022)
- Secretary (2018-2019)
- Executive committee board (2018-)

#### Reviewer:

##### Grants/Awards:

2022 NASA Early Career Faculty Review Panel

2022 NSF Research Traineeship (NRT) Program Review Panel

2019 NASA Fellowship (Program Officer, Brenda Collins)

Scientific Reports, IEEE Electron Device Letters (EDL), Applied Physics Letters (APL), IEEE Transactions on Circuits and Systems II (TCAS-II), IEEE Transaction on Electron Devices (TED), IEEE Journal of Electron Devices Society (J-EDS), IEEE Access, IEEE Transactions on Quantum Engineering, IEEE Transactions on Semiconductor Manufacturing, IEEE Transaction on Nanotechnology (TNANO), Diamond & Related Materials (DRM), IET Electronics Letters, IEEE International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), ECS Journal of Solid State Science and Technology, IET Circuits, Devices & Systems, Journal of the Electrochemical Society, Electrochemical and Solid-State Letters, Solid-State Electronics, Power Electronic Devices and Components.

#### Outreach:

- Organizer and speaker: QuDIT Testbed Workshop – the 'Real World Quantum Computing @ LLNL' 2022, 2023
- Summer class by Silicon Tech Academy, “Intro to Python Programming - with Machine Learning & Quantum Computing Applications”. Two-week hands-on class for 8<sup>th</sup>-9<sup>th</sup> grade students (free for social-economically disadvantaged students). 2022.
- Judge: The Synopsys Championship (the Santa Clara County science fair for students in grades 6-12), Sciencepalooza! (for students in grades 9-12 in East San José)
- Summer Class: “Introduction to Python Programming and Machine Learning” 6/30/2020-7/1/2020 for Downtown College Prep high school students.

## Grants

**2018 Fall – present: US\$3.3M awarded (US\$1.9M to Wong’s Lab)**

#### Extramural:

- G1. **Sumsung Inc**, Cryogenic MOSFET Mobility Extraction and Modeling, US\$75,000, *PI* (100%) (2023)
- G2. **Atomera Inc**, Cryogenic Characterization of MST Devices, US\$50,052, *PI* (100%) (2022)
- G3. **Atomera Inc**, Circuit Simulation, Carrier Transport Physics Characterization, and BTI Reliability Modeling of MST, US\$11,751, *PI* (100%) (2022)
- G4. **Atomera Inc**, Circuit Simulation, Carrier Transport Physics Characterization, and BTI Reliability Modeling of MST, US\$50K, *PI* (100%) (2021)
- G5. **National Science Foundation**, CAREER: Understanding and Modeling of Cryogenic Semiconductor Device Physics down to 4.2K, US\$500K, **PI** (100%) (2021-2026)

- G6. **National Science Foundation**, FMSG: Cyber: Cybermanufacturing of Wide-Bandgap Semiconductor Devices Enabled by Simulation Augmented Machine Learning, US\$500K, **co-PI** (40%) (2021-2023) (PI: Dr. Yuhao Zhang)
- G7. **National Science Foundation**, Collaborative Research: NRT-QL: A Program for Training a Quantum Workforce, US\$739K, **co-PI** (33%) (2021-2026) (PI: Dr. Hilary Hurst)
- G8. **National Science Foundation**, RET site: Multidisciplinary Teacher Research Experience in Engineering (M-TREE), US\$600K, **Senior Personnel** (3.3%) (2021-2024) (PI: Dr. Liat Rosenfeld)
- G9. **Applied Materials Inc**, Power Device Simulation and Optimization, US\$65K, **PI** (100%) (2021-2020)
- G10. **Synopsys Inc**, Materials Modeling Research Project, US\$15K, **PI** (100%) (2020-2021)
- G11. **Atomera Inc**, Modeling and Simulation of MST, US\$75K, **PI** (100%) (2020)
- G12. **Department of Energy, PowerAmerica**, Development of Low-Cost Graduate Course with Virtual Fab and Hands-on Circuit Lab Experience to Prepare Students to Work in the SiC Industry in Silicon Valley, US\$50K, **PI** (50%) (2019-2020)
- G13. **NASA**, Chip Design for Self-Healing Electronics, US\$ 50K, **PI** (100%) (2019-2020)
- G14. **Department of Defense, Naval Surface Warfare Center Crane Division**, Radiation Hardness Projection and Optimization of sub-10nm Technology Node SRAM through Design-Technology-Co-Optimization (DTCO) Simulations, US\$ 26K, **PI** (100%) (2019)
- G15. **Atomera Inc**, Modeling and Simulation of MST, US\$27.5K, **PI** (100%) (2019)
- G16. **Synopsys Inc**, Materials Modeling Research Project, US\$30K, **PI** (100%) (2019-2020)
- G17. **Atomera Inc**, CMOS applications of MST film using TCAD, US\$25K, **PI** (100%) (2019)

**Internal (SJSU):**

- G18. **SJSU, AMDT Endowment Funding**, US\$300K, **PI** (100%) (2022-2023)
- G19. **SJSU, The Level-Up Grant**, Development of Cryogenic Transistor Model for Quantum Computing Peripherals, US\$9,350, **PI** (100%) (2020-2021)
- G20. **SJSU COE**, Design Technology Co-Optimization (DTCO) Framework for Neuromorphic Computing: from Device to System, US \$100,000, **PI** (34%) (2019-2020)

**Patents**

- P1. **Hiu Yung Wong**. Variable Channel Doping in Vertical Transistor. US Provisional Patent App. US 63/223,459, 2021.
- P2. **Hiu Yung Wong**, Nelson de Almeida Braga and Rimvydas Mickevicius. Machine Learning for Optimizing Setups for Accurate, Speedy and Robust TCAD Simulations. U.S. Patent No. 11,348,017. Issued May 17, 2022.
- P3. **Hiu Yung Wong** and Rimvydas Mickevicius. Using Threading Dislocations in GaN/Si System to generate Physical Unclonable Function (PUF). U.S. Patent No. 11,152,313. Issued October 5, 2021.
- P4. **Hiu Yung Wong**, Nelson de Almeida Braga and Rimvydas Mickevicius. Constricted Junction-less FinFET/ Nanowire/ Nanosheet with normally-off VTH, high ION and low leakage. U.S. Patent No. 10,777,638. Issued September 15, 2020.
- P5. **Hiu Yung Wong** and Rimvydas Mickevicius. A new local Band-to-Band Tunneling (BTBT) model for more accurate and speedy TCAD simulations. U.S. Patent No. 10,769,339. Issued September 8, 2020.
- P6. **Hiu Yung Wong**, Victor Moroz, and Qiang Lu. Anti-punch-through implant or its extension/variations as heater for on-chip self-heating and self-annealing. U.S. Patent No. 10,699,914. Issued June 30, 2020.
- P7. **Hiu Yung Wong**, Nelson de Almeida Braga and Rimvydas Mickevicius. Normally-off Gallium Oxide Field-Effect Transistor. U.S. Patent No. 10,644,107. Issued May 5, 2020.
- P8. **Hiu Yung Wong**, Nelson de Almeida Braga and Rimvydas Mickevicius. Monolithically Integrated III-Nitride Cascode Circuit for High Voltage Application. U.S. Patent No. 10,403,625. Issued September 3, 2019.
- P9. **Hiu Yung Wong**, Nelson de Almeida Braga and Rimvydas Mickevicius. Heterojunction Field Effect Transistor Device with Serially Connected Enhancement Mode and Depletion Mode Gate Regions. U.S. Patent No. 10,128,232. Issued November 13, 2018.

- P10. **Hiu Yung Wong**, Nelson de Almeida Braga and Rimvydas Mickevicius. Tined gate to control threshold voltage in a device formed of materials having piezoelectric properties. U.S. Patent No. 9,837,523. filed 13 Apr 2016 and issued 5 Dec 2017.
- P11. Eunha Kim, Wen Yu, Minh-Van Ngo, Kyunghoon Min and **Hiu Yung Wong**. Forming metal-semiconductor films having different thicknesses within different regions of an electronic device. US Patent 7,880,221, filed 19 Dec 2008, and issued 1 Feb 2011.
- P12. Eunha Kim, Wen Yu, Minh-Van Ngo, Kyunghoon Min and **Hiu Yung Wong**. Forming metal-semiconductor films having different thicknesses within different regions of an electronic device. US Patent 7,482,217, filed 3 Dec 2007, and issued 27 Jan 2009.

## Awards

- 2022 Curtis W. McGraw Research Award (ASEE Engineering Research Council)
- AMDT Endowed Chair Professor (2022-)
- NSF CAREER Award, 2021
- The 2021 Newnan Brothers Award for Faculty Excellence, “demonstrate excellence in some combination of teaching, service to students, and/or research”.
- San Jose State University Grants Academy award, 2019
- Synopsys Outstanding Contribution to Results Award (For supporting foundry FinFET simulation), 2013
- Synopsys Outstanding Contribution to Results Award (For leading power device simulation), 2010
- Synopsys Excellence Award (1 out of every ~500 employees), 2010
- Sir Edward Youde Memorial Fellowships for Overseas Studies, 2001

## Book

**Hiu Yung Wong**, *Introduction to Quantum Computing: From a Layperson to a Programmer in 30 Steps*. Switzerland: Springer International Publishing, 2022. <https://doi.org/10.1007/978-3-030-98339-0>. ISBN-10: 3030983382.

## Book Chapter

Chatterjee, B., Shoemaker, D., **Wong, H.**, and Choi, S, "AlGaIn/GaN HEMT device physics and electrothermal modeling," Chapter 6 in *Thermal Management of Gallium Nitride Electronics*, Marko J. Tadjer and Travis J. Anderson, Editors, Woodhead Publishing, 2022.

## Peer-Reviewed Journal Papers (+: Supervised Students)

- J1. **Hiu Yung Wong**, “TCAD Simulation Models, Parameters, and Methodologies for beta-Ga2O3 Power Devices,” *ECS Journal of Solid State Science and Technology*, 12 055002, 2023. DOI 10.1149/2162-8777/accfbc.
- J2. Pranay Doshi, **Hiu Yung Wong**, Daniel H. Gutierrez, Arlene Lopez, Dennis Nordlund and Ram Prasad Gandhiraman, "Printing of electromagnetic interference shielding materials," 2023 *Flex. Print. Electron.* 8 025003. DOI 10.1088/2058-8585/acc879
- J3. **Hiu Yung Wong**, Prabjot Dhillon<sup>+</sup>, Kristin Beck, and Yaniv Jacob Rosen, "A Simulation Methodology for Superconducting Qubit Readout Fidelity," *Solid-State Electronics*, Volume 201, March 2023, 108582. <https://doi.org/10.1016/j.sse.2022.108582>.
- J4. Ravi Tiwari, Meng Duan, Mohit Bajaj, Denis Dolgos, Lee Smith, **Hiu Yung Wong**, and Souvik Mahapatra, "A Physics-based TCAD Framework for NBTI," *Solid-State Electronics*, <https://doi.org/10.1016/j.sse.2022.108573>.

- J5. **Albert Lu**<sup>+</sup>, Adam Elwailly<sup>+</sup>, Yuhao Zhang and **Hiu Yung Wong**, "Study of Vertical Ga<sub>2</sub>O<sub>3</sub> FinFET Short Circuit Ruggedness using Robust TCAD Simulation," *ECS J. Solid State Sci. Technol*, 2022. <https://doi.org/10.1149/2162-8777/ac9e73>
- J6. **Albert Lu**<sup>+</sup>, Jordan Marshall<sup>+</sup>, Yifan Wang, Ming Xiao, Yuhao Zhang, and **Hiu Yung Wong**, "Vertical GaN Diode BV Maximization through Rapid TCAD Simulation and ML-enabled Surrogate Model," *Solid-State Electronics*, Volume 198, December 2022, 108468, <https://doi.org/10.1016/j.sse.2022.108468>.
- J7. **V. Eranki**<sup>+</sup>, N. Yee and **H. Y. Wong**, "Out-of-Training-Range Synthetic FinFET and Inverter Data Generation Using a Modified Generative Adversarial Network," in *IEEE Electron Device Letters*, vol. 43, no. 11, pp. 1810-1813, Nov. 2022, doi: 10.1109/LED.2022.3207784.
- J8. **Tom Jiao**<sup>+</sup> and **Hiu Yung Wong**, "Robust Cryogenic Ab-initio Quantum Transport Simulation for LG=10nm Nanowire," *Solid-State Electronics*, Volume 197, 2022, 108440, doi.org/10.1016/j.sse.2022.108440.
- J9. **H. Y. Wong**, "Ab Initio Study of HfO<sub>2</sub>/Ti Interface VO/Oi Frenkel Pair Formation Barrier and VO Interaction With Filament," in *IEEE Transactions on Electron Devices*, vol. 69, no. 9, pp. 5130-5137, Sept. 2022, doi: 10.1109/TED.2022.3188227.
- J10. **P. Quibuyen**<sup>+</sup>, T. Jiao<sup>+</sup>, and **H. Y. Wong**, "A Software-Circuit-Device Co-Optimization Framework for Neuromorphic Inference Circuits," in *IEEE Access*, vol. 10, pp. 41078-41086, 2022, doi: 10.1109/ACCESS.2022.3167709.
- J11. **Prabjot Dhillon**<sup>+</sup> and **Hiu Yung Wong**, "A Wide Temperature Range Unified Undoped Bulk Silicon Electron and Hole Mobility Model," in *IEEE Transactions on Electron Devices*, doi: 10.1109/TED.2022.3152471. (2022)
- J12. **Thomas Lu**<sup>+</sup>, Varada Kanchi<sup>+</sup>, Kashyap Mehta<sup>+</sup>, Sagar Oza<sup>+</sup>, Tin Ho<sup>+</sup>, and **Hiu Yung Wong**, "Rapid MOSFET Contact Resistance Extraction from Circuit using SPICE Augmented Machine Learning without Feature Extraction," in *IEEE Transactions on Electron Devices*, vol. 68, no. 12, pp. 6026-6032, Dec. 2021, doi: 10.1109/TED.2021.3123092.
- J13. J. Lundh, D. Shoemaker, A. G. Birdwell, J. D. Weil, L. M. De La Cruz, P. B. Shah, K. G. Crawford, T. G. Ivanov, **H. Y. Wong**, and S. Choi, "Thermal performance of diamond field-effect transistors," *Appl. Phys. Lett.* 119, 143502 (2021); <https://doi.org/10.1063/5.0061948>.
- J14. **Harsaroop Dhillon**<sup>+</sup>, Kashyap Mehta<sup>+</sup>, Ming Xiao, Boyan Wang, Yuhao Zhang, and **Hiu Yung Wong**, "TCAD-Augmented Machine Learning with and without Domain Expertise," in *IEEE Transactions on Electron Devices*, vol. 68, no. 11, pp. 5498-5503, Nov. 2021, doi: 10.1109/TED.2021.3073378.
- J15. **A. Elwailly**<sup>+</sup>, J. Saltin<sup>+</sup>, M. J. Gadlage and **H. Y. Wong**, "Radiation Hardness Study of LG = 20 nm FinFET and Nanowire SRAM Through TCAD Simulation," in *IEEE Transactions on Electron Devices*, vol. 68, no. 5, pp. 2289-2294, May 2021, doi: 10.1109/TED.2021.3067855.
- J16. **K. Mehta**<sup>+</sup> and **Hiu Yung Wong**, "Prediction of FinFET Current-Voltage and Capacitance-Voltage Curves Using Machine Learning With Autoencoder," in *IEEE Electron Device Letters*, vol. 42, no. 2, pp. 136-139, Feb. 2021, doi: 10.1109/LED.2020.3045064.
- J17. Fei Ding, **Hiu-Yung Wong** and Tsu-Jae King Liu, "Design optimization of Sub-5nm Node Nanosheet Field Effect Transistors to Minimize Self-Heating Effects," *Journal of Vacuum Science and Technology B*, B 39, 013201 (2021); <https://doi.org/10.1116/6.0000675>. (**Editor's Pick**)
- J18. **Hiu Yung Wong**, Ming Xiao, Boyan Wang, Yan Ka Chiu<sup>+</sup>, Xiaodong Yan, Jiahui Ma, Kohei Sasaki, Han Wang, and Yuhao Zhang, "TCAD-Machine Learning Framework for Device Variation and Operating Temperature Analysis With Experimental Demonstration," in *IEEE Journal of the Electron Devices Society*, vol. 8, pp. 992-1000, 2020, doi: 10.1109/JEDS.2020.3024669.
- J19. Uma Sharma, Meng Duan, Himanshu Diwakar, Karansingh Thakor, **Hiu Yung Wong**, Steve Motzny, Denis Dolgos and Souvik Mahapatra, "TCAD Framework for HCD Kinetics in Low VD Devices Spanning Full VG/VD Space," in *IEEE Transactions on Electron Devices*, doi: 10.1109/TED.2020.3021360.
- J20. Cyril Buttaya, **Hiu-Yung Wong**, Boyan Wang, Ming Xiao, Christina DiMarino and Yuhao Zhang, "Surge Current Capability of Ultra-Wide-Bandgap Ga<sub>2</sub>O<sub>3</sub> Schottky Diodes," *Microelectronics Reliability*, Volume 114, November 2020, 113743. 10.1016/j.microrel.2020.113743.
- J21. **K. Mehta**<sup>+</sup>, S. S. Raju<sup>+</sup>, M. Xiao, B. Wang, Y. Zhang and **H. Y. Wong**, "Improvement of TCAD Augmented Machine Learning Using Autoencoder for Semiconductor Variation Identification and Inverse Design," in *IEEE Access*, vol. 8, pp. 143519-143529, 2020, doi: 10.1109/ACCESS.2020.3014470.
- J22. **J. Saltin**<sup>+</sup>, N. C. Dao, P. H. W. Leong and **H. Y. Wong**, "Energy Filtering Effect at Source Contact on Ultra-Scaled MOSFETs," in *IEEE Journal of the Electron Devices Society*, vol. 8, pp. 662-667, 2020, doi: 10.1109/JEDS.2020.2981251.
- J23. **Hiu Yung Wong** and Armand Tenkeu<sup>+</sup>, "Advanced TCAD Simulation and Calibration of Gallium Oxide Vertical Transistor," *ECS Journal of Solid State Science and Technology* 9 (3), 035003, 2020.
- J24. **Hiu-Yung Wong**, Denis Dolgos, Lee Smith, Rimvydas V. Mickevicius, "Modified Hurkx Band-to-Band-Tunneling Model for Accurate and Robust TCAD Simulations," *Microelectronics Reliability*, Volume 104, January 2020, 113552.

- J25. Boyan Wang, Ming Xiao, Xiaodong Yan, **Hiu Yung Wong**, Jiahui Ma, Kohei Sasaki, Han Wang, and Yuhao Zhang, "High-voltage vertical Ga<sub>2</sub>O<sub>3</sub> power rectifiers operational at high temperatures up to 600 K", *Appl. Phys. Lett.* 115, 263503 (2019); <https://doi.org/10.1063/1.5132818>.
- J26. Ravi Tiwari, Narendra Parihar, Karansingh Thakor, **Hiu Yung Wong**, Steve Motzny, Munkang Choi, Victor Moroz and Souvik Mahapatra, "A 3-D TCAD Framework for NBTI, Part-I: Implementation Details and FinFET Channel Material Impact, in *IEEE Transactions on Electron Devices*, vol. 66, no. 5, pp. 2086-2092, May 2019.
- J27. Ravi Tiwari, Narendra Parihar, Karansingh Thakor, **Hiu Yung Wong**, Steve Motzny, Munkang Choi, Victor Moroz and Souvik Mahapatra, "A 3-D TCAD Framework for NBTI, Part-II: Impact of Mechanical Strain, Quantum Effects and FinFET Dimension Scaling, in *IEEE Transactions on Electron Devices*, vol. 66, no. 5, pp. 2093-2099, May 2019.
- J28. **Hiu Yung Wong**, Nelson Braga and R. V. Mickevicius, "Enhancement Mode Recessed Gate and Cascade Gate Junctionless Nanowire with Low Leakage and High Drive Current," in *IEEE Transactions on Electron Devices*, vol. 65, no. 9, pp. 4004-4008, Sept. 2018.
- J29. P. Pfäffli, **H.Y. Wong**, X. Xu, L. Silvestria, X.W. Lin, T. Yang, R. Tiwari, S. Mahapatra, S. Motzny, V. Moroz and Terry Ma, "TCAD Modeling for Reliability," *Microelectronics Reliability*, Volumes 88–90, September 2018, Pages 1083-1089.
- J30. **Hiu Yung Wong**, Nelson Braga and R. V. Mickevicius, "Prediction of highly scaled hydrogen-terminated diamond MISFET performance based on calibrated TCAD simulation," *Diamond and Related Materials*, Volume 80, November 2017, Pages 14-17.
- J31. **Hiu Yung Wong**, Nelson Braga, R. V. Mickevicius, " Normally-off GaN HFET based on Layout and Stress Engineering ", *IEEE Electron Device Letters*, 37 (12), 1621-1624.
- J32. Subrat Mishra, **Hiu Yung Wong**, Ravi Tiwari, Ankush Chaudhary, Rakesh Rao, Victor Moroz and Souvik Mahapatra, "TCAD-based NBTI Predictive Model for Sub-20nm node Device Design Considerations", *IEEE Transactions on Electron Devices*, 63 (12), 4624-4631.
- J33. Jin-Woo Han, **Hiu-Yung Wong**, Nelson Braga, Dong-II, Moon and Meyya Meyyappan, "Stringer Gate FinFET on Bulk Substrate", *IEEE Transactions on Electron Devices*, 63 (9), 3432-3438.
- J34. Victor Moroz, **Hiu Yung Wong**, Munkang Choi, Nelson Braga, R. V. Mickevicius, Yuhao Zhang, Thomas Palacios, "The Impact of Defects on GaN Device Behavior: Modeling Dislocations, Traps, and Pits", *ECS J. Solid State Sci. Technol.* 2016, volume 5, issue 4, P3142-P3148. **(INVITED PAPER)**
- J35. Yuhao Zhang, Min Sun, **Hiu-Yung Wong**, Yuxuan Lin, Puneet Srivastava, Christopher Hatem, Mohamed Azize, Daniel Piedra, Lili Yu, Takamichi Sumitomo, Nelson de Almeida Braga, Vidas Mickevicius, and Tomás Palacios, "Origin and Control of Off-State Leakage Current in GaN-on-Si Vertical Diodes ", *IEEE Transactions on Electron Devices*, Vol. 62, No.7, 2155-2161, 2015.
- J36. **Hiu Yung Wong**, H. Takeuchi, T-J King, M. Ameen, and A. Agarwal, "Elimination of Poly-Si Gate Depletion for Sub-65nm CMOS Technologies by Excimer Laser Annealing", *IEEE Electron Device Letters*, Vol. 26, No. 4, pp. 234-236, 2005.
- J37. Neil N. H. Ching, **H. Y. Wong**, Wen J. Li, Philip H. W. Leong and Zhiyu Wen, "A laser-micromachined multi-modal resonating power transducer for wireless sensing systems", *Sensors and Actuators A: Physical*, Vol. 97-98, pp. 685-690, 2002.
- J38. P. H. W. Leong, C. W. Sham, W. C. Wong, **H. Y. Wong**, W. S. Yuen and M. P. Leong, "A Bitstream Reconfigurable FPGA Implementation of the WSAT algorithm", *IEEE Transactions on VLSI Systems*, Vol. 9, No. 1, pp. 197-201, 2001
- J39. W. J. Li, G. M. H. Chan, N. N. H. Ching, P. H. W. Leong and **H. Y. Wong**, "Dynamical Modelling and Simulation of a Laser-micromachined Vibration-based Micro Power Generator", *International Journal of Nonlinear Sciences and Simulation*, Vol. 1, pp. 345-353, 2000.

### **Peer-Reviewed Conference Papers (+: Supervised Students)**

- C1. **N. Yee**<sup>+</sup>, A. Lu<sup>+</sup>, Y. Wang, M. Porter, Y. Zhang, and **H.-Y. Wong**, "Rapid Inverse Design of GaN-on-GaN Diode with Guard Ring Termination for BV and (VFQ)<sup>-1</sup> Co-optimization", Accepted to 2023 35th International Symposium on Power Semiconductor Devices and ICs (ISPSD), Hong Kong, 2023.
- C2. H. Takeuchi, R. J. Mears, M. Hytha, D. J. Connelly, P. E. Nicollan and **H. -Y. Wong**, "Remote Control of Doping Profile, Silicon Interface, and Gate Dielectric Reliability via Oxygen Insertion into Silicon Channel," 2022 IEEE International Meeting for Future of Electron Devices, Kansai (IMFEDK), 2022, pp. 1-4, doi: 10.1109/IMFEDK56875.2022.9975306.
- C3. **H. Y. Wong**, "Quantum Computing and Information Specialization in Electrical Engineering Master Degree," 2022 IEEE International Conference on Quantum Computing and Engineering (QCE), 2022, pp. 693-696, doi: 10.1109/QCE53715.2022.00093.

- C4. **Albert Lu**<sup>+</sup>, Jordan Marshall<sup>+</sup>, Yifan Wang, Ming Xiao, Yuhao Zhang, and **Hiu Yung Wong**, "Vertical GaN Diode BV Maximization through Rapid TCAD Simulation and ML-enabled Surrogate Model," Accepted to 2022 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), 2022.
- C5. **Tom Jiao**<sup>+</sup> and **Hiu Yung Wong**, "Robust Cryogenic Ab-initio Quantum Transport Simulation for LG=10nm Nanowire," Accepted to 2022 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), 2022.
- C6. **Hiu Yung Wong**, Yaniv Jacob Rosen, Kristin Beck, Prabjot Dhillon<sup>+</sup>, and Jonathan L. Dubois, "A Simulation Methodology for Superconducting Qubit Readout Fidelity," Accepted to 2022 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), 2022.
- C7. Ravi Tiwari, Meng Duan, Mohit Bajaj, Denis Dolgos, Lee Smith, **Hiu Yung Wong**, and Souvik Mahapatra, "A Complete TCAD Framework for NBTI," Accepted to 2022 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), 2022.
- C8. **H. Dhillon**<sup>+</sup>, Y. J. Rosen, K. Beck and **H. Y. Wong**, "Simulation of Single-shot Qubit Readout of a 2-Qubit Superconducting System with Noise Analysis," 2022 IEEE Latin American Electron Devices Conference (LAEDC), 2022, pp. 1-4, doi: 10.1109/LAEDC54796.2022.9908196.
- C9. **A. Zaman**<sup>+</sup> and **H. Y. Wong**, "Study of Error Propagation and Generation in Harrow-Hassidim-Lloyd (HHL) Quantum Algorithm," 2022 IEEE Latin American Electron Devices Conference (LAEDC), 2022, pp. 1-4, doi: 10.1109/LAEDC54796.2022.9908231.
- C10. **Shubhankar Sharma**<sup>+</sup>, Yi Zheng and **Hiu Yung Wong**, "Short Circuit Ruggedness of Trench Filled Superjunction Devices," 2022 IEEE Latin American Electron Devices Conference (LAEDC), Cancun, Mexico, 2022, pp. 1-4, doi: 10.1109/LAEDC54796.2022.9908223.
- C11. **P. Quibuyen**<sup>+</sup>, T. Jiao<sup>+</sup>, and **H. Y. Wong**, "Effect of ReRAM Neuromorphic Circuit Array Variation and Fault on Inference Accuracy," 2022 IEEE 4th International Conference on Artificial Intelligence Circuits and Systems (AICAS), Incheon, Korea, Republic of, 2022, pp. 13-16, doi: 10.1109/AICAS54282.2022.9869936.
- C12. **V. Eranki**<sup>+</sup>, T. Lu<sup>+</sup>, and **H. Y. Wong**, "Comparison of Manifold Learning Algorithms for Rapid Circuit Defect Extraction in SPICE-Augmented Machine Learning," 2022 IEEE 19th Annual Workshop on Microelectronics and Electron Devices (WMED), 2022, pp. 1-4, doi: 10.1109/WMED55302.2022.9758032.
- C13. **Fanus Arefaine**<sup>+</sup>, Meng Duan, Ravi Tiwari, Lee Smith, Souvik Mahapatra, and **Hiu Yung Wong**, "Using Long Short-Term Memory (LSTM) Network to Predict Negative-Bias Temperature Instability," 2021 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), 2021, pp. 60-63, doi: 10.1109/SISPAD54002.2021.9592531.
- C14. **Hector Morrell**<sup>+</sup> and **Hiu Yung Wong**, "Study of using Quantum Computer to Solve Poisson Equation in Gate Insulators," 2021 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), 2021, pp. 69-72, doi: 10.1109/SISPAD54002.2021.9592604.
- C15. **Prabjot Dhillon**<sup>+</sup>, Nguyen Cong Dao, Philip H. W. Leong, and **Hiu Yung Wong**, "TCAD Modeling of Cryogenic nMOSFET ON-State Current and Subthreshold Slope," 2021 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), 2021, pp. 255-258, doi: 10.1109/SISPAD54002.2021.9592586.
- C16. Daniel Connelly, **Hiu Yung Wong**, Richard Burton, Hideki Takeuchi, Robert Mears, "RFSOI n-MOSFET OI-Layer Ground-Plane Engineering with Quasi-3D Simulations," 2021 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), 2021, pp. 263-267, doi: 10.1109/SISPAD54002.2021.9592543.
- C17. **A. Raol**<sup>+</sup>, T. Jiao, C. Shashidhara and **H. Y. Wong**, "Fully-Coupled Simulation of the Temperature Effect on Negative Capacitance Ferroelectric Devices," 2021 IEEE Latin America Electron Devices Conference (LAEDC), 2021, pp. 1-4, doi: 10.1109/LAEDC51812.2021.9437945.
- C18. A. Shimbori, **H. Y. Wong** and A. Q. Huang, "Comprehensive Comparison of Fabricated 1.6-kV Punch-Through Design Ni/n-SiC Schottky Barrier Diode with Ar<sup>+</sup> Implant Edge Termination and Heterojunction p-NiO/n-SiC Diode," 2021 IEEE Latin America Electron Devices Conference (LAEDC), 2021, pp. 1-4, doi: 10.1109/LAEDC51812.2021.9437747.
- C19. **Johan Saltin**<sup>+</sup>, Adam Elwailly<sup>+</sup>, and **Hiu Yung Wong**, "FinFET and Nanowire SRAM Radiation Hardness Studies using Ab initio-TCAD Simulation Framework," Government Microcircuit Applications & Critical Technology Conference (GOMAC), 32-1, 2021.
- C20. **H. Cao**<sup>+</sup>, T. Lam<sup>+</sup>, H. Nguyen<sup>+</sup>, A. Venkatraman, D. Parent and **H. Y. Wong**, "Study of ReRAM Neuromorphic Circuit Inference Accuracy Robustness using DTCO Simulation Framework," 2021 IEEE Workshop on Microelectronics and Electron Devices (WMED), 2021, pp. 1-4, doi: 10.1109/WMED49473.2021.9425210.
- C21. **Sophia Susan Raju**<sup>+</sup>, Boyan Wang, Kashyap Mehta<sup>+</sup>, Ming Xiao, Yuhao Zhang, and **Hiu Yung Wong**, "Application of Noise to Avoid Overfitting in TCAD Augmented Machine Learning," IEEE 2020 International Conference on Simulation of Semiconductor Processes and Devices, pp. 351-354, doi: 10.23919/SISPAD49475.2020.9241654.
- C22. **Hiu Yung Wong**, "Calibrated Si Mobility and Incomplete Ionization Models with Field Dependent Ionization Energy for Cryogenic Simulations," IEEE 2020 International Conference on Simulation of Semiconductor Processes and Devices, pp.193-196, doi: 10.23919/SISPAD49475.2020.9241599.
- C23. **A. Nguyen**<sup>+</sup>, H. Nguyen<sup>+</sup>, S. Venimadhavan<sup>+</sup>, A. Venkatraman, D. Parent and **H. Y. Wong**, "Fully Analog ReRAM Neuromorphic Circuit Optimization using DTCO Simulation Framework," 2020 International Conference on Simulation of



Semiconductor Processes and Devices (SISPAD), Kobe, Japan, 2020, pp. 201-204, doi: 10.23919/SISPAD49475.2020.9241635.

- C24. **Adam Elwailly**<sup>+</sup>, Ming Xiao, Yuhao Zhang, and **Hiu Yung Wong**, "Design Space of Vertical Ga<sub>2</sub>O<sub>3</sub> Junctionless FinFET and its Enhancement with Gradual Channel Doping," IEEE Workshop on Wide Bandgap Power Devices and Applications in Asia 2020, pp. 41-45.
- C25. Cyril Buttaya, **Hiu-Yung Wong**, Boyan Wang, Ming Xiao, Christina DiMarino and Yuhao Zhang, "Surge Current Capability of Ultra-Wide-Bandgap Ga<sub>2</sub>O<sub>3</sub> Schottky Diodes," The 31st European Symposium on Reliability of Electron Devices, Failure Physics and Analysis, Athens, 2020.
- C26. Shuntaro Fujii, Hideki Takeuchi, Soichi Morita, Tatsushi Yagi, Shohei Hamada, Toshiro Sakamoto, Shinji Kawaguchi, Naoki Ishigami, Atsushi Okamoto, Shuji Ikeda, **Hiu-Yung Wong**, Robert J. Mears and Tsutomu Miyazaki, "Analysis of the Effects of Boron Transient Enhanced Diffusion on Threshold Voltage Mismatch in Steep Retrograde Doping NMOSFETs with Inserted Oxygen Layers," 2020 IEEE International Symposium on the Physical and Failure Analysis of Integrated Circuits (IPFA), Singapore, Singapore, 2020, pp. 1-4, doi: 10.1109/IPFA49335.2020.9260584 .
- C27. Atsushi Shimbori, **Hiu Yung Wong** and Alex Q. Huang, "Fabrication and Analysis of a Novel High Voltage Heterojunction p-NiO/n-Ga<sub>2</sub>O<sub>3</sub> Diode," 2020 32nd International Symposium on Power Semiconductor Devices and ICs (ISPSD), Vienna, Austria, 2020, pp. 218-221, doi: 10.1109/ISPSD46842.2020.9170054.
- C28. Robert J Mears, Hideki Takeuchi, Yi-Ann Chen, Richard Burton, Shuyi Li, Robert J. Stephenson, Marek Hytha, Nyles W. Cody, K. Doran Weeks, Dmitri Choutov, Daniel Connelly and **Hiu-Yung Wong**, "Applications of Oxygen Inserted Silicon Devices in Power and RF: (invited)," 2020 4th IEEE Electron Devices Technology & Manufacturing Conference (EDTM), Penang, Malaysia, 2020, pp. 1-4, doi: 10.1109/EDTM47692.2020.9117944. **(INVITED)**
- C29. **Hiu Yung Wong**, Johan Saltin<sup>+</sup> and Yan Ka Chiu<sup>+</sup>, "SRAM Radiation Effect Study using DTCO Approach," 16th International Conference on Reliability and Stress-related Phenomena in Nano and Microelectronics, San Jose, CA, Nov, 2019. **(INVITED)**
- C30. **Johan Saltin**<sup>+</sup> and **Hiu Yung Wong**, "TCAD Simulation of FinFET and Nanosheet Radiation Hardness," 16th International Conference on Reliability and Stress-related Phenomena in Nano and Microelectronics, San Jose, CA, Nov, 2019. (Poster)
- C31. **Johan Saltin**<sup>+</sup>, Shiyang Tian, Fei Ding and **Hiu Yung Wong**, "Novel Doping Engineering Techniques for Gallium Oxide MOSFET to Achieve High Drive Current and Breakdown Voltage," IEEE 7th Workshop on Wide Bandgap Power Devices and Applications, Raleigh, NC, 2019, pp261-264.
- C32. **Khoa Huynh**<sup>+</sup>, Johan Saltin<sup>+</sup>, Jin-Woo Han, Meyya Meyyappan and **Hiu Yung Wong**, "Study of Layout Dependent Radiation Hardness of FinFET SRAM using Full Domain 3D TCAD Simulation," IEEE SOI-3D-Subthreshold Microelectronics Technology Unified Conference, San Jose, CA, 2019.
- C33. **J. Saltin**<sup>+</sup>, N. C. Dao, P. H. W. Leong, and **H. Y. Wong**, "Degradation of Sub-Threshold Slope in Ultra-Scaled MOSFETs due to Energy Filtering at Source Contact," IEEE SOI-3D-Subthreshold Microelectronics Technology Unified Conference, San Jose, CA, 2019.
- C34. **K. Huynh**<sup>+</sup>, A. C. Tenkeu<sup>+</sup>, K.P. Pun and **H. Y. Wong**, "TCAD-Spice Co-Simulation of Ferroelectric Capacitor as an Electrically Trimmable On-Chip Capacitor in Analog Circuit", IEEE SOI-3D-Subthreshold Microelectronics Technology Unified Conference, San Jose, CA, 2019.
- C35. **Bankapalli Yogeswara Sarat**<sup>+</sup> and **Hiu Yung Wong**, "TCAD Augmented Machine Learning for Semiconductor Device Failure Troubleshooting and Reverse Engineering", IEEE 2019 International Conference on Simulation of Semiconductor Processes and Devices, Udine, Italy, 2019, pp. 21-24.
- C36. Ravi Tiwari, Narendra Prihar, Karansingh Thakor, **Hiu-Yung Wong** and Souvik Mahapatra, "TCAD Framework to Estimate the NBTI Degradation in FinFET and GAA NSFET Under Mechanical Strain", IEEE 2019 International Conference on Simulation of Semiconductor Processes and Devices, Udine, Italy, 2019, pp. 9-12.
- C37. **Hiu Yung Wong**, Nelson Braga, Jie Liu and R. V. Mickevicius, " Studies of Stress Effects on the Electrical Performance of AlGa<sub>N</sub>/Ga<sub>N</sub> HEMTs through Ab-Initio Calculation and TCAD Simulation," 13th International Conference on Nitride Semiconductors 2019 (ICNS-13). (Poster)
- C38. **H. Y. Wong**, F. Ding, N. Braga, R. V. Mickevicius, "Normally-off Dual-gate Ga<sub>2</sub>O<sub>3</sub> Planar MOSFET and FinFET with High Current and Breakdown Voltage," International Symposium on Power Semiconductor Devices and ICs 2018, pp. 379-382. (Poster)
- C39. **Hiu Yung Wong**, Munkang Choi, Ravi Tiwari and Souvik Mahapatra, "On the NBTI of Junction-less Nanowire and Novel Operation Scheme to Minimize NBTI Degradation in Analog Circuits", 2018 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), pp. 172-175.
- C40. N. Parihar, R. Tiwari, C. Ndiaye, M. Arabi, S. Mhira, **H. Wong**, S. Motzny, V. Moroz, V. Huard and S. Mahapatra, "Modeling of Process (Ge, N) Dependence and Mechanical Strain Impact on NBTI in RMG HKMG SiGe FDSOI p-

- MOSFETs and p-FinFETs", 2018 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), pp. 167-171.
- C41. P. Pfäffli, **H.Y. Wong**, X. Xu, L. Silvestria, X.W. Lin, T. Yang, R. Tiwari, S. Mahapatra, S. Motzny, V. Moroz and Terry Ma, "TCAD Modeling for Reliability," in 29th European Symposium on Reliability of Electron Devices, Failure Physics and Analysis (**INVITED**)
- C42. Pooya Jannaty, **Hiu-Yung Wong**, Ricardo Borges, Lee Smith, "A physics-based industry-proven TCAD simulator for superconducting electronics," Applied Superconductivity Conference 2018. (POSTER)
- C43. **Hiu Yung Wong**, Nelson Braga and R. V. Mickevicius, "A Physical Model of the Abnormal Behaviour of Hydrogen-Terminated Diamond MESFET," 2017 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), Kamakura, 2017, pp. 333-336.
- C44. **Hiu Yung Wong**, Subrat Mishra, Souvik Mahapatra, Steve Motzny and Victor Moroz, "FinFET NBTI Degradation Reduction and Recovery Enhancement through Hydrogen Incorporation and Self-Heating", 2017 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), Kamakura, 2017, pp. 101-104.
- C45. S. Mishra, **H. Y. Wong**, R. Tiwari, N. Parihar, R. Rao, S. Motzny, V. Moroz and S. Mahapatra, "Predictive TCAD for NBTI Stress-Recovery in Various Device Architectures and Channel Materials", 2017 IEEE International Reliability Physics Symposium (IRPS), Monterey, CA, 2017, pp. 6A-3.1-6A-3.8.
- C46. **Hiu Yung Wong**, Nelson Braga, R. V. Mickevicius, "AlGaIn/GaN Rake-Gate HFET: A Novel Normally-Off HFET based on Stress and Layout Engineering", 2016 International Conference on Simulation of Semiconductor Processes and Devices (SISPAD), Nuremberg, 2016, pp. 61-64.
- C47. **Hiu Yung Wong**, Oleg Penzin, Nelson Braga, R. V. Mickevicius, "Quantum Correction in AlGaIn/GaN Transistor Simulations Using Modified Local Density Approximation (MLDA)," 2016 IEEE International Conference on Electron Devices and Solid-State Circuits (EDSSC), Hong Kong, 2016, pp. 239-242.
- C48. Victor Moroz, **Hiu Yung Wong**, and Munkang Choi, "Modeling Extended Defects in Semiconductor Devices, "ECS PRIME 2016. ECS Transactions 75 (4), 143-152 (**INVITED PAPER**)
- C49. **Hiu Yung Wong**, Nelson Braga, R. V. Mickevicius and Jie Liu, "Study of the effects of barrier and passivation nitride stresses on AlGaIn/GaN HEMT performance using TCAD simulation," Wide Bandgap Power Devices and Applications (WiPDA), 2015 IEEE 3rd Workshop on, Blacksburg, VA, 2015, pp. 24-27.
- C50. Y. Zhang\*, **H.-Y. Wong\***, M. Sun, S. Joglekar, N. A., R. V. Mickevicius, and T. Palacios, "Design space and origin of off-state leakage in GaN vertical power diodes," 2015 IEEE International Electron Devices Meeting (IEDM), Washington, DC, USA, 2015, pp. 35.1.1-35.1.4. (**\*Equal contribution**)
- C51. M. Shur, M. Gaevski, R. Gaska, G. Simin, **H. Y. Wong**, N. Braga, and R. Mickevicius, "Power Loss Reduction in Perforated-Channel HFET Switches", ECS Trans. 2015 66(1): 179-183. doi:10.1149/06601.0179ecst (**INVITED PAPER**)
- C52. **H. Y. Wong**, N. Braga, R. V. Mickevicius, F. Gao and T. Palacios, "Study of AlGaIn/GaN HEMT degradation through TCAD simulations," Simulation of Semiconductor Processes and Devices (SISPAD), 2014 International Conference on, Yokohama, 2014, pp. 97-100.
- C53. R Gaska, M Gaevski, J Deng, **H Wong**, N Braga, RV Mickevicius, M Shur, III-Nitride Perforated Channel FET for High-Efficiency Power Switches and Amplifiers, International Workshop on Nitride Semiconductor 2014
- C54. M. Shur, M. Gaevski, J. Deng, R. Gaska, **H. Wong**, N. Braga, V. Mickevicius, and G. Simin, Superior Frequency Characteristics of Perforated Channel HFET, The Lester Eastman Conference on High Performance Devices, 5 – 7 Aug. 2014, Cornell Univ. p. S4-P4
- C55. R Gaska, J Yang, D Billingsley, B Khan, G Simin, **HY Wong**, N Braga, X Hu, J Deng, M Shur, R Mickevicius, "Insulated-Gate Integrated III-Nitride RF Switches", Compound Semiconductor Integrated Circuit Symposium (CSICS), 2011 IEEE.
- C56. **H. Y. Wong**, H. Takeuchi, A. Padilla, T.-J. King, M. Ameen, and A. Agarwal, "Pulsed excimer laser annealing for meeting near-term front end processes gate-stack challenges," presented at the 207th Meeting of the Electrochemical Society, Symposium K1 (Quebec City, Canada), May 2005.
- C57. **H.-Y. Wong**, H. Takeuchi, T.-J. King, M. Ameen, and A. Agarwal, "Reduced poly-Si gate depletion effect by pulsed excimer laser annealing," presented at the 205th ECS Meeting, Advanced Short-Time Thermal Processing for Si-Based CMOS Devices II Symposium (San Antonio, TX, USA), May 2004. (**INVITED PAPER**)
- C58. H. Takeuchi, **H. Y. Wong**, D. Ha, and T.-J. King, "Impact of oxygen vacancies on high-k gate dielectric engineering," International Electron Devices Meeting Technical Digest, pp. 829-832, 2004.
- C59. **H. Y. Wong**, K. Shin, and M. Chan, "The Gate Misalignment Effects of the Sub-threshold Characteristics of sub-100nm DG-MOSFETs", 2002 IEEE Hong Kong Electron Devices Meeting Proceedings, pp. 91-94, June 22, 2002, Hong Kong

- C60. Neil N. H. Ching, **Hiu Yung Wong**, Wen J. Li, and Philip H. W. Leong, "A laser-micromachined vibrational to electrical power transducer for wireless sensing systems", 11th International Conference on Solid-State Sensors and Actuators, (Transducers '01 / Eurosensors XV), Munich, Germany, June 2001.
- C61. Neil N. H. Ching, Gordon M. H. Chan, Wen J. Li, **Hiu Yung Wong**, and Philip H. W. Leong, "PCB-integrated Micro-generator Arrays for Wireless Systems", International Symposium on Smart Structures and Microsystems, Oct. 19-21, 2000, Hong Kong.
- C62. Wen J. Li, Philip H. W. Leong, Terry C. H. Hong, **Hiu Yung Wong**, and Gordon M. H. Chan, "Infrared Signal Transmission by a Laser-micromachined vibration-induced power generator", Proceedings of the 43rd IEEE Midwest Symposium on Circuits and Systems, August 8-11, pp. 236-239, 2000
- C63. **H. Y. Wong**, W. S. Yuen, K. H. Lee and P. H. W. Leong, "A Runtime Reconfigurable Implementation of the GSAT Algorithm", the Proceedings of the Ninth International Workshop on Field Programmable Logic and Applications (FPL'99) Glasgow, UK, pp. 526-531, 1999

### **Invited Conference Workshops and Tutorials:**

- W1.** **Hiu Yung Wong**, Tutorial: Introduction to Quantum Computing: from Algorithm to Hardware. IEEE Quantum Week 2023.
- W2.** **Hiu Yung Wong**, Tutorial: Introduction to Quantum Computing: from Algorithm to Hardware. ISQED conference 2023
- W3.** **Hiu Yung Wong**, Workshop 1: Combination of TCAD and Machine Learning, SISPAD 2020
- W4.** **Hiu Yung Wong**, (Ultra) Wide Bandgap Material Process and Device TCAD Simulation Methodologies, WiPDA-Asia, 2020

### **Invited Presentations (+: Supervised Students)**

- I1. **Hiu Yung Wong**, "Introduction to Quantum Hardware", 25th New Frontiers in Computing (NFIC) 2023 co-organized by NATEA and IEEE-Computer Society Santa Clara Valley, May 2023.
- I2. **Hiu Yung Wong**, "Introduction to Quantum Computing: from Algorithm to Hardware", Washington DC Quantum Computing Meetup, April, 2023. (100 attendees)
- I3. **Hiu Yung Wong**, "Introduction to Quantum Computing", Lynbrook High School, San Jose, March 2023.
- I4. CSU Exemplars in Physics, Oct. 2022
- I5. **Hiu Yung Wong**, "Introduction to Quantum Computing", Synopsys, Inc., Mountain View, CA, September, 2022. (40 attendees)
- I6. **Hiu Yung Wong**, "Introduction to Quantum Computing", Zen4Quantum, August, 2022. (40 attendees)
- I7. **Bay Area Semiconductor Work Force Development Mini-Workshop**, August. 2022.
- I8. **Hiu Yung Wong**, "Introduction to Quantum Computing", eBay, Inc., San Jose, CA, August. 2022. (30 attendees)
- I9. **Hiu Yung Wong**, "A Beginner's Guide to Quantum Computing Webinar", FormFactor, Inc, Milpitas, CA, August. 2022. (>300 attendees)
- I10. **Hiu Yung Wong**, "Introduction to Quantum Computing", Fujitsu Research of America, Sunnyvale, CA, May, 2022. (30 attendees)
- I11. **Hiu Yung Wong**, "TCAD/SPICE-Augmented Machine Learning for Defect and Variation Study", IEEE-EDS Santa Clara Valley/San Francisco Chapter October Seminar, 2021.
- I12. **Hiu Yung Wong**, Nelson Braga, and R. V. Mickevicius, TCAD modeling of hydrogen-terminated diamond FET for RF Applications, Mat Science 2020, San Francisco, CA, November 5-7, 2020.
- I13. **Hiu Yung Wong**, "TCAD to SPICE: MST RF Simulation as an Example", Atomera, Inc., Saratoga, CA, Sept. 2020.
- I14. **Hiu Yung Wong**, "TCAD Seminar: Using Machine Learning in TCAD", Synopsys, Inc., Mountain View, CA, Aug. 2020.
- I15. **Hiu Yung Wong**, Modeling, Calibration and Simulation of Ga<sub>2</sub>O<sub>3</sub> Vertical Diode and FinFET in TCAD, Workshop on Compound Semiconductor Materials and Devices WOCSEMMAD, 2020.
- I16. **Hiu Yung Wong**, "TCAD Augmented Machine Learning for Semiconductor Device Failure Troubleshooting and Reverse Engineering", Silvaco, Inc., Santa Clara, CA, Oct 2019.
- I17. **Hiu Yung Wong** and Johan Saltin<sup>+</sup>, TCAD Simulation of Novel Gallium Oxide Power Device with High On/Off Ratio, Workshop on Compound Semiconductor Materials and Devices WOCSEMMAD, 2019.
- I18. Rake-Gate AlGa<sub>N</sub>/Ga<sub>N</sub> normally off HEMTs, Workshop on Compound Semiconductor Materials and Devices WOCSEMMAD, 2018.
- I19. **Hiu Yung Wong**, "Selected TCAD Topics on More Moore and More than Moore", Seminar Talk in Department of Electronic Engineering, Chinese University of Hong Kong, Hong Kong, 2017.

120. Low RC-constant Perforated-Channel HFET, Workshop on Compound Semiconductor Materials and Devices WOCSEMMAD, 2014,
121. **Hiu Yung Wong**, “Elimination of Poly-Si Gate Depletion for Sub-65nm CMOS Technologies by Excimer Laser Annealing”, West Coast Junction Technology Group Meeting, Sunnyvale, CA, 2005.
122. **Hiu Yung Wong**, Laser Annealing Technology, AMD, Sunnyvale, CA, 2005.

### **Other Technical Publications**

- Subrat Mishra, Narendra Parihar, Rakesh Rao, and Souvik Mahapatra, **Hiu Yung Wong**, Steve Motzny, and Victor Moroz, “NBTI Modeling in Sentaurus Device”, Synopsys TCAD Newsletter December 2016.
- TCAD Application Note “Device Monte Carlo Simulation Methodology of Two-dimensional FinFET Slices”, 2012
- TCAD Application Note “Simulation of Normally Off GaN MISFET with Piezo Neutralization Technique”, 2011
- TCAD Application Note “Simulation of Normally Off AlGaIn/GaN HFET with p-Type GaN Gate and AlGaIn Buffer”, 2011
- SRC Report on tunable work function gate technology options (2-Aug-2004). Publication: P009712 (with K. Shin).
- 0.35um CMOS Process on Six-inch Wafers Baseline Report IV, A. Horvath, S. Parsa and **H. Y. Wong**, Memorandum No. UCB/ERL M05/15, Electronics Research Laboratory, College of Engineering, UC Berkeley
- **H Wong**, N Braga, S Tian, R Borges, “Simulations Enhance The Development Of Power Devices”, compound semiconductor, 2011

### **Education**

- **Program created:** Master of Science in Quantum Technology at San Jose State University, 2023
- **Specialization created:** Quantum Computing and Information Specialization, MS Electrical Engineering
- **Courses created**  
EE222, EE225, EE226, EE274

- **Lecturer**

EE124. Electronic Design II, San Jose State University, (53 students), Spring 2023  
 EE274. Quantum Computing Architectures, San Jose State University, (12 students), Spring 2023  
 EE124. Electronic Design II, San Jose State University, (60 students), Fall 2022  
 EE225. Introduction to Quantum Computing, San Jose State University, (24 students), Fall 2022  
 EE124. Electronic Design II, San Jose State University, (52 students), Spring 2022  
 EE226. Cryogenic Nanoelectronics, San Jose State University, (16 students), Spring 2022  
 EE124. Electronic Design II, San Jose State University, (59 students), Fall 2021  
 EE225. Introduction to Quantum Computing, San Jose State University, (14 students), Fall 2021  
 EE124. Electronic Design II, San Jose State University, (57 students), Spring 2021  
 EE224. High Speed CMOS Circuits, San Jose State University, (26 students), Spring 2021  
 EE124. Electronic Design II, San Jose State University, (70 students), Fall 2020  
 EE222. Advanced Integrated Device, San Jose State University, (16 students), Spring 2020  
 EE124. Electronic Design II, San Jose State University, (57 students), Spring 2020  
 EE225. Introduction to Quantum Computing, San Jose State University, (11 students), Spring 2020  
 EE124. Electronic Design II, San Jose State University, (56 students), Fall 2019  
 EE224. High Speed CMOS Circuits, San Jose State University, (18 students), Fall 2019  
 EE124. Electronic Design II, San Jose State University, (58 students), Spring 2019  
 EE222. Semiconductor Devices II, San Jose State University, (13 students), Spring 2019  
 EE124. Electronic Design II, San Jose State University, (68 students), Fall 2018  
 EE224. High Speed CMOS Circuits, San Jose State University, (31 students), Fall 2018

- **Teaching Assistant experience (from Devices to Digital/Analog Circuits to Computer Architectures):**  
Microelectronic Devices and Circuits (EE 105), EECS, UC Berkeley, Fall 2005, *evaluation: 4.4/5*  
Analog Integrated Circuits (EE 140), EECS, UC Berkeley, Fall 2001, *evaluation: 4.4/5*

Computer System Architectures (CEG 3420), CSE, CUHK, Spring 2001

Digital Circuits (CEG 3470), CSE, CUHK, Fall 2000

Computer System Architectures (CEG 3420), CSE, CUHK, Spring 2000, *Best TA Award*

Digital Circuits (CEG 3470), CSE, CUHK, Fall 1999, *Best TA Award*

- **10-year TCAD and device physics training experience to customers**